

KOPIOINNISTEET OVAT MINIMI 0,025 AVG, 0,020 MIN .. SYÖTÄ EI KÄYTETÄ

Pakkaa värittömällä läpinäkyvällä kuparikalvolla, 25 PCS / pussi, laita kuivausaine kylkeen, laita kosteusindikaattorikortti yläpuolelle

toimittaja: [Pcb-suunnittelu Kiinassa](#), [pcb valmistaja Kiinassa](#), [Pienikokoinen PCB-valmistaja](#)

Tuotteen Kuvaus:

lyhyitä tietoja

| | | | | | |
|--------------------|--|---------------------|-----------------------|-----------------------|---|
| Place of origin: | Guangdong China (Mainland) | Brand name: | O-Leading | Model number: | Assembling the power bank pcb pcba manufacturer |
| Basic Material: | EM-370(5) Mid-TG | Copper thickness: | 1oz | Plate thickness: | 0.1-5mm |
| Minimum Hole Size: | 0.1mm | Minimum Line width: | 0.2mm | Minimum Line spacing: | 0.2mm |
| Surface treatment: | Immersion gold, OSP | Colour: | black | price: | \$ 0.1- \$ 10 |
| Applicable to: | Lead, mobile phone, air Air conditioners, washing machines | character: | Industrial controller | the size: | 0.01m3-10m3 |
| Certificates: | ISO9001, UL, RoHS, SGS | Q / CTN: | 10pcs-100pcs | Type design: | Customer requirement |
| the weight: | 0.01kg-5kg | MOQ: | 10 pieces | | |

Packing & Delivery

| | |
|--------------------|--|
| Packaging Details: | 16-year-old professional OEM client Board Manufacturer |
| Delivery detail: | 7-12days. |

Packing & Delivery

Packaging Details: 16-year-old professional OEM client Board Manufacturer

Delivery detail: 7-12days.

| paragraph | 2017 | | 2018 ~ 2020 | | 2021 ~ 2023 | |
|--|---|-----------|-------------|-----------|-------------|-----------|
| | Amount | Sample | Amount | Sample | Amount | Sample |
| Number of layers | 32 | 42 | 38 | 44 | 42 | 48 |
| Min. Line / Spacing (µm) | 50/50 | 40/45 | 40/45 | 40/40 | 35/40 | 35/35 |
| Min. Drilling hole Diameter (mm) | 0,15 | 0.10 | 0,15 | 0.10 | 0,15 | 0.10 |
| Aspect Ratio PTH | 14: 1 | 16: 1 | 16: 1 | 18: 1 | 18: 1 | 20: 1 |
| N + C + N, | 4 + C + 4 | 5 + C + 5 | 5 + C + 5 | 6 + C + 6 | 5 + C + 5 | 6 + C + 6 |
| Any layer Relationship | 5 + 2 + 5 | 6 + 2 + 6 | 5 + 2 + 5 | 6 + 2 + 6 | 5 + 2 + 5 | 6 + 2 + 6 |
| Filling of plates through | YES | - | YES | - | YES | - |
| Minimum Core Thickness (Excluding copper) (µm) | 50 | 40 | 40 | thirty | 40 | thirty |
| Minimum Laser Drill Diameter (µm) | 75 | 65 | 65 | 50 | 50 | 40 |
| Via at the Funeral Hole / styling through | YES | - | YES | - | YES | - |
| material | FR4, Megtron, Nelco, Rogers, Heavy Copper, etc. | | | | | |
| Built-in capacitor printed circuit board | YES | - | YES | - | YES | - |
| Surface process | Lead-free HASL, ENIG, OSP, silver with immersion, tin of immersion, Flash of gold, Golden finger coating, Selective solid gold coating, Flaking solder mask, carbon ink | | | | | |